

220 SERIES MICRO  
STRIPPERSPE 30 SERIES ION  
BEAM ETCHING400 SERIES MICRO  
SPUTTERING

800 SERIES MICRO RIE

900 SERIES MICRO  
PECVDD

## 220 SERIES MICRO STRIPPER

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The Stripping/Cleaning System Series 220 low temperature plasma system is designed for production use in photoresist stripping of high resolution integrated circuits, organic ashing, surface cleaning and treatment, and trace elements studies.

The electrode system is supplied with a unique Linear Matrix electrode system, rods running the length of the reaction chamber following the inner perimeter of the chamber and spaced two inches from the chamber wall. Alternate rods of the Linear Matrix electrode system are RF driving and ground, therefore the discharge is from rod to rod. This discharge produces a modern upstream plasma system with virtually no ionic bombardment and exceptional uniformity unattainable in any other system. When used with the optional Faraday Cage the substrates are totally protected from ionic bombardment.

This action results in a process that is very controllable and is the preferred technique in use today. The Stripping/Cleaning System provides a means of reliable production of sub-micron devices.

The Technics 220 Series Micro Stripper, provides ultimate precision for stripping of:

- \* Photoresist Layers
- \* Devices Failure Analysis
- \* Laboratory Samples
- \* Surfaces Treatment of Hybrid Circuits
- \* Etching IC Packages during Failure Analysis
- \* Remove Passivation Layers

The system's computer controls and displays all system functions (except safety interlocks). It is menu driven for ease of use and may store any number of recipes with any number of cycles. Automatic data logging and other operator convenience will maximize the accuracy and efficiency of your R&D or pilot line production.

The 220 Series Micro Stripper with this unique RADIAL ROD electrode system providing uniformity not found in any other system.

You can depend on the 220 Series Micro Stripper to deliver consistent, uniform and reproducible etching or stripping of semiconductor films and other device structures.



*Paper--Technical analysis employing the methodology available via eMailed*

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OTHER PRODUCTS:

[300 Ion Mill](#) - [400 Micro Sputtering](#) - [800 Micro RIE](#) - [900 Micro PECVD](#)